

Title (en)

DEVICE FOR DISSIPATING HEAT FROM A HEAT SOURCE LOCATED IN A HOUSING

Title (de)

ANORDNUNG ZUR ABFÜHRUNG VON WÄRME EINER IN EINEM GEHÄUSE ANGEORDNETEN WÄRMEQUELLE

Title (fr)

DISPOSITIF SERVANT A DISSIPER LA CHALEUR PROVENANT D'UNE SOURCE DE CHALEUR PLACEE DANS UN BOITIER

Publication

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Application

**EP 98919048 A 19980306**

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Abstract (en)

[origin: WO9842169A2] According to the invention, the device has a primary cooling element (K1) located inside a housing (G) and a secondary cooling element (K2) located outside the housing (G). The cooling elements are connected via a heat conduction element (P), in order to dissipate heat from the housing (G), said connection being heat-conductive and mechanically moveable. The inventive device for dissipating heat has the particular advantage of drastically reducing the risk of hairline cracks forming in the heat conduction element (P) as a result of vibrations, and could therefore be used effectively in an industrial environment.

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IPC 8 full level

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